



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **F0107-02** DATE: 07/15/2001
Product Affected: NW1034, NW6000, NW6001, NW6002
 NW6003, NW6005, NW6006
Manufacturing Location Affected: All
Date Effective: 10/15/2001

MEANS OF DISTINGUISHING CHANGED DEVICES:

- ☒ Product Mark
☐ Back Mark
☐ Date Code
☐ Other

Contact: Dasharath Patel

Title: QA Manager, FIFO/Telecom Products

Attachment:: ☒ Yes ☐ No

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Samples: Available upon request

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DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
☐ Wafer Fabrication Process
☒ Assembly Process
☒ Equipment
☒ Material
☒ Testing
☒ Manufacturing Site
☐ Data Sheet
☒ Other Packing and orientation.

As a result of Integrated Device Technology, Inc (IDT) acquisition of Newave Semiconductor Corp., USA, there will a consolidation of operations. This will consist of assembly, test, backend and packing changes. Please see attachments for detailed description of changes.

At this point, there will be no changes to wafer fab facilities and processes.

Devices affected: NW1034, NW6000, NW6001, NW6002, NW6003, NW6005, NW6006

RELIABILITY/QUALIFICATION SUMMARY: Available upon request

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____

☐ *Approval for shipments prior to effective date.*

Name/Date: _____

E-Mail Address: _____

Title: _____

Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____

DATE: _____

ATTACHMENT - PCN #: F0107-01

PCN Summary

PCN Type: Assembly, Test, Backend and Packing changes

Commodity NW1034, NW6000, NW6001, NW6002, NW6003, NW6005, NW6006

Forecast or Execute Execute

Planned or Unplanned Planned

Data Sheet Change No Change

Detail of Change See attached

Conversion schedule (Estimated) 15-Oct-01

Sample Availability

Upon Request

Production Shipments

15-Oct-01



Description of Changes

This PCN will replace PDN F-01-02 for device NW6000AS, NW6001AS and NW6002CS. These devices will receive continued support by IDT.

The following changes will be implemented on all existing Newave products:

Manufacturing Site Change:

Newave assembly, test and backend facilities will be transferred selectively to IDT ISO 9001 & 9002 certified assembly, test and backend facilities. Please refer to pages 4-8 for details

Packing/Shipping Change:

Existing Newave packing procedures will be replaced by IDT packing procedures. These consist of different units per tray or tube and moisture classification (as in accordance with JEDEC standard J-STD-020). Please refer to pages 4-8 for details.

Top Mark Change:

Newave logo ("NW") will be replaced by IDT logo "IDT". Also, the Newave top mark format will be replaced with IDT top mark format. This consists of mark orientation change on selective packages. Please refer to pages 4-8 for details.

Effective Dates

This applies to all changes mentioned in section "Description of Changes".

Manufacturing Site Change, Packing/Shipping Change:

Effective October 15th, 2001, customers will receive existing Newave products that are assembled, tested, backend processed at either Newave or IDT approved facilities. This includes also changes in the packing and shipping process from Newave to IDT procedures.

Top Mark Change:

Effective October 1st, 2001, for a certain period of time, customers will receive devices with either the Newave or the IDT logo and top mark format. There will be no mixed shipment of top marked units within one shipping carrier unit.



Attachment

Manufacturing Site Change

Assembly Location

ASAT, Hong Kong
AMKOR Tech, Philippines
AMKOR Tech, Buchon, Korea
AMKOR Tech, Bupyung, Korea
AMKOR Tech, Kwangju, Korea
AMKOR Tech, Seoul, Korea
UNISEM, Malaysia

Assembly lot# contains letter

T
P
N
Y
D
I
Z

Mark/Test/Backend locations

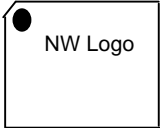
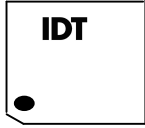
IDT Penang
IDT, Philippines
Unisem
Amkor Tech, Korea
ASAT, Hong Kong
Amkor Tech, Philippines



Top mark date code contains letter

P
M
U
A
X
D



Attachment

Device Name		Assembly Location		Test Location		Packing/Shipping	
From NW	To IDT	From	To	From	To	From	To
NW1034BQ	821034DN	Caesar/ASAT	ASAT/AMKOR	ASAT	ASAT/IDT-PNG	50/84/Tray	84/Tray
Mark Orientation		Device Top Mark				Moisture Classification	
From	To	From	To			From	To
		(NW Logo) NW1034BQ (Assembly Lot#) YYWW	(IDT Logo) 821034DN ZYYWWL			N/A	N/A
				Z: Stepping; L: Mark Location			

Device Name		Assembly Location		Test Location		Packing/Shipping	
From NW	To IDT	From	To	From	To	From	To
NW6000AS		ATES	AMKOR	NA	NA	100/Tube	98/Tube
Mark Orientation		Device Top Mark				Moisture Classification	
From	To	From	To			From	To
		(NW Logo) NW6000AS (Assembly Lot#) YYWW	(IDT Logo) NW6000AS ZYYWWL			JEDEC Level 3	JEDEC Level 1
				Z: Stepping; L: Mark Location			



Attachment

Device Name		Assembly Location		Test Location		Packing/Shipping	
		From	To	From	To	From	To
NW6001AS		ATES	AMKOR	NA	NA	50/Tube	48/Tube
Mark Orientation		Device Top Mark				Moisture Classification	
From	To	From	To			From	To
<div>NW logo</div> <div>○</div>	<div>IDT</div> <div>○</div>	(NW Logo) NW6001AS (Assembly Lot#) YYWW	(IDT Logo) NW6001AS ZYYWWL		Assm Lot#	JEDEC Level 3	JEDEC Level 1
				Z: Stepping; L: Mark Location			

Device Name		Assembly Location		Test Location		Packing/Shipping	
		From	To	From	To	From	To
NW6002CS		OSET	Unisem	NA	NA	32/Tube	31/Tube
Mark Orientation		Device Top Mark				Moisture Classification	
From	To	From	To			From	To
<div>NW logo</div> <div>○</div>	<div>IDT</div> <div>○</div>	(NW Logo) NW6002CS (Assembly Lot#) YYWW	(IDT Logo) NW6002CS ZYYWWL		Assm Lot#	JEDEC Level 3	JEDEC Level 1
				Z: Stepping; L: Mark Location			



Attachment

Device Name		Assembly Location		Test Location		Packing/Shipping	
		From	To	From	To	From	To
NW6003AS		OSET	Unisem/AMKOR	N/A	N/A	32/Tube	31/Tube
Mark Orientation		Device Top Mark				Moisture Classification	
From	To	From	To			From	To
<div>NW logo</div> <div>○</div>	<div>IDT</div> <div>○</div>	(NW Logo) NW6003AS (Assembly Lot#) YYWW	(IDT Logo) NW6003AS ZYYWWL			JEDEC Level 3	JEDEC Level 1
				Z: Stepping; L: Mark Location			

Device Name		Assembly Location		Test Location		Packing/Shipping	
		From	To	From	To	From	To
NW6005AS		OSET	Unisem/AMKOR	N/A	N/A	38/Tube	37/Tube
Mark Orientation		Device Top Mark				Moisture Classification	
From	To	From	To			From	To
<div>NW logo</div> <div>○</div>	<div>IDT</div> <div>○</div>	(NW Logo) NW6005AS (Assembly Lot#) YYWW	(IDT Logo) NW6005AS ZYYWWL		Assm Lot#	JEDEC Level 3	JEDEC Level 1
				Z: Stepping; L: Mark Location			



Device Name		Assembly Location		Test Location		Packing/Shipping	
		From	To	From	To	From	To
NW6006AS		OSET	Unisem/AMKOR	N/A	N/A	38/Tube	37/Tube
Mark Orientation		Device Top Mark				Moisture Classification	
From	To	From	To			From	To
<div>NW logo</div> <div>○</div>	<div>IDT</div> <div>○</div>	(NW Logo) NW6006AS (Assembly Lot#) YYWW	(IDT Logo) NW6006AS ZYYWWL			JEDEC Level 3	JEDEC Level 1
				Assm Lot#			
				Z: Stepping; L: Mark Location			